

(19) World Intellectual Property  
Organization  
International Bureau



(43) International Publication Date  
16 June 2005 (16.06.2005)

PCT

(10) International Publication Number  
**WO 2005/055351 A1**

(51) International Patent Classification<sup>7</sup>: **H01M 8/02**,  
C08K 7/06, 7/24, 3/38

(21) International Application Number:  
PCT/JP2004/018448

(22) International Filing Date: 3 December 2004 (03.12.2004)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:  
2003-407765 5 December 2003 (05.12.2003) JP  
60/528,828 12 December 2003 (12.12.2003) US

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(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

**Published:**

- with international search report
- before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: ELECTROCONDUCTIVE RESIN COMPOSITION AND MOLDED PRODUCT THEREOF

(57) Abstract: An electroconductive resin composition, comprising at least: a multi-component polymer-type resin binder (A) comprising a dispersed phase and a continuous phase, and having a number-average particle size of dispersed phase of 0.001-2 µm, and an electroconductive material (B) in the form of powder and/or fiber. The electroconductive resin composition may preferably be used for a fuel cell separator.



WO 2005/055351 A1